

ABSTRACT OF THE DISCLOSURE

A connection method and a connection structure, using solder bumps, for component-side pad electrodes and substrate-side pad electrodes, and inspecting methods for the connection state thereof which are adaptable to high density mounting, and which allow the miniaturization of the product formed by mounting a surface-mount component onto a substrate. Substrate-side pad electrodes are arranged inside a component-corresponding region A; the length of the substrate-side pad electrodes is set to be larger than that of the corresponding component-side pad electrode; an IC chip (surface-mount component) is placed on the substrate so that each of the solder bumps is opposed to a predetermined substrate-side pad electrode; and the solder bumps are melted by heating, thereby connecting each of the component-side pad electrodes and one of the substrate-side pad electrodes through the solder.